

AON7406-VB Datasheet N-Channel 30-V (D-S) MOSFET

V _{DS}	30	V
R _{DS(on),typ} V _{GS} =10V	13	mΩ
RDS(on),typ VGS=4.5V	19	mΩ
ID	30	Α

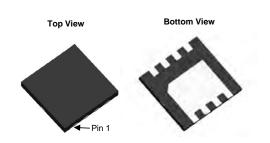
FEATURES

- · Halogen-free
- Trench Power MOSFET
- 100 % R_g and UIS Tested

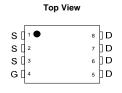


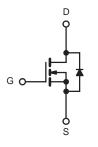
APPLICATIONS

- DC/DC Conversion
 - Low-Side Switch
- Notebook PC
- Gaming



DFN 3x3 EP





N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS T _A = 25 °C, unless otherwise noted					
Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V_{DS}	30	V	
Gate-Source Voltage		V_{GS}	± 20	V	
	T _C = 25 °C		30		
Continuous Drain Current (T _{.I} = 150 °C)	T _C = 70 °C	I _D	20		
Continuous Diairi Current (1) = 150 °C)	T _A = 25 °C	טי [21.5 ^{b, c}		
	T _A = 70 °C	1 1	17.1 ^{b, c}	Α	
Pulsed Drain Current		I _{DM}	100		
Continuous Source-Drain Diode Current	T _C = 25 °C	- I _S	13		
	T _A = 25 °C	'5	3.1 ^{b, c}		
Single Pulse Avalanche Current	L = 0.1 mH	I _{AS}	10		
Avalanche Energy	L = 0.111111	E _{AS}	5	mJ	
Maximum Power Dissipation	$T_C = 25 ^{\circ}C$		60		
	$T_C = 70 ^{\circ}C$	P _D	30	w	
	T _A = 25 °C] ' '	3.7 ^{b, c}	• • • • • • • • • • • • • • • • • • • •	
	T _A = 70 °C	<u>] </u>	2.4 ^{b, c}		
Operating Junction and Storage Temperature	e Range	T _J , T _{stg}	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient ^{b, d}	t ≤ 10 s	R _{thJA}	27	34	°C/W
Maximum Junction-to-Foot (Drain)	Steady State	R_{thJF}	6	7.5	C/ V V

Notes:

- a. Based on $T_C = 25$ °C.
- b. Surface Mounted on 1" x 1" FR4 board.
- c. t = 10 s
- d. Maximum under Steady State conditions is 85 °C/W.



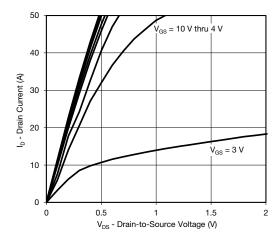
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 1 \text{ mA}$	30			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	J 250 A		27		mV/°C	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	- I _D = 250 μA		- 5.6			
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = 250 \mu A$	1.0		3.0	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
Zana Oata Vallana Brain Oamani		V _{DS} = 30 V, V _{GS} = 0 V			1		
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 30 V, V _{GS} = 0 V, T _J = 55 °C			10	μA	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	30			Α	
		V _{GS} = 10 V, I _D = 15 A		13		m()	
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = 4.5 V, I _D = 10 A		19		mΩ	
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 15 A		75		S	
Dynamic ^b							
Input Capacitance	C _{iss}				900		
Output Capacitance	C _{oss}	$V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$			236	pF	
Reverse Transfer Capacitance	C _{rss}				20		
T. 10 . 0		V _{DS} = 15 V, V _{GS} = 10 V, I _D = 10 A			20	nC	
Total Gate Charge	Q_g	50 00 5			9		
Gate-Source Charge	Q_{gs}	$V_{DS} = 15 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 10 \text{ A}$			2.1		
Gate-Drain Charge	Q_{gd}				0.7	1	
Gate Resistance	R _g	f = 1 MHz	0.2	1.1	2.2	Ω	
Turn-On Delay Time	t _{d(on)}			8	16		
Rise Time	t _r	$V_{DD} = 15 \text{ V}, R_{L} = 1.5 \Omega$		16	30		
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 10 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 1 \Omega$		17	35	1	
Fall Time	t _f			7	15		
Turn-On Delay Time	t _{d(on)}			14	30	ns	
Rise Time	t _r	$V_{DD} = 15 \text{ V}, R_{L} = 1.5 \Omega$		50	100		
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 10 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$		16	30		
Fall Time	t _f			8	18		
Drain-Source Body Diode Characteristi	cs			•			
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C			13		
Pulse Diode Forward Current ^a	I _{SM}				100	A	
Body Diode Voltage	V _{SD}	I _S = 3 A			1.2	V	
Body Diode Reverse Recovery Time	t _{rr}				40	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	1 40 A 41/4 400 A/2 T 0500			20	nC	
Reverse Recovery Fall Time	t _a	$I_F = 10 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 \text{ °C}$		12.5			
Reverse Recovery Rise Time	t _b	1		7.5		ns	

Notes:

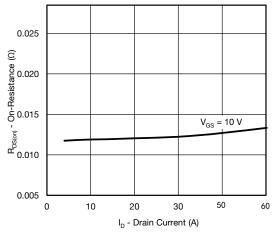
- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%$
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

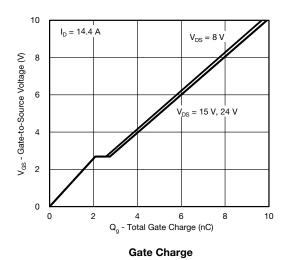


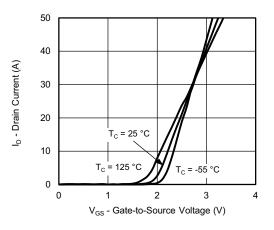


Output Characteristics

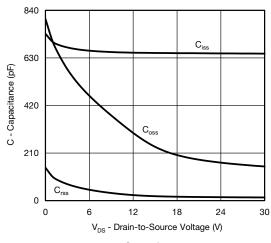


On-Resistance vs. Drain Current

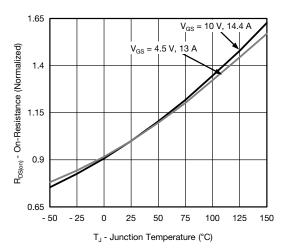




Transfer Characteristics

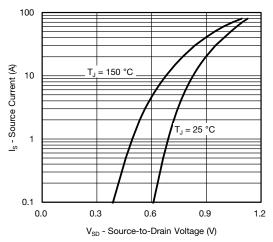


Capacitance

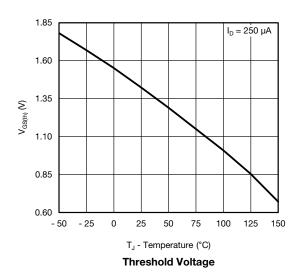


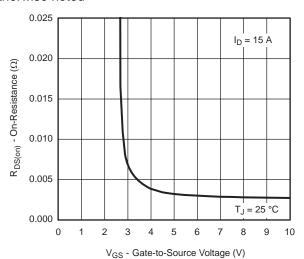
On-Resistance vs. Junction Temperature



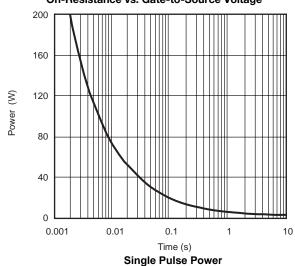


Source-Drain Diode Forward Voltage





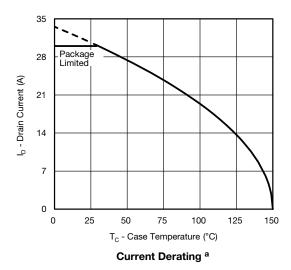
On-Resistance vs. Gate-to-Source Voltage

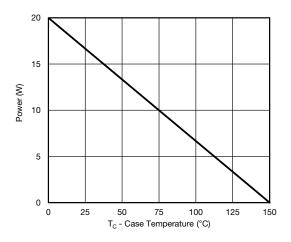


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Safe Operating Area, Junction-to-Ambient





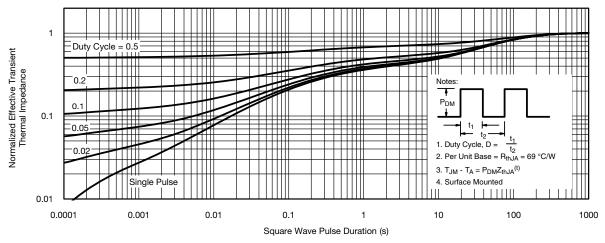


Power, Junction-to-Case

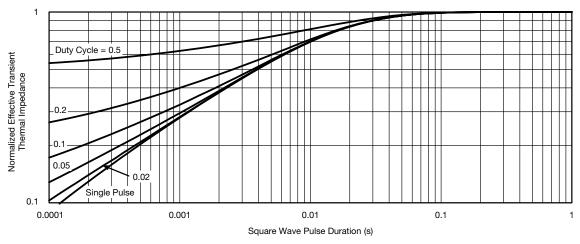
Note

a. The power dissipation P_D is based on T_J max. = 25 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



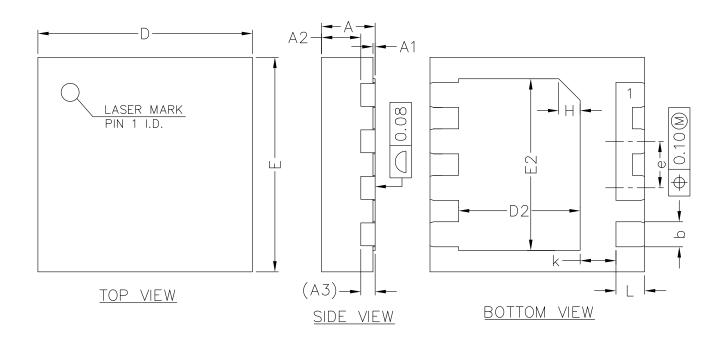


Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case







COMMON DIMENSIONS
(UNITS OF MEASURE=MILLIMETER)

SYMBOL	MIN	NOM	MAX	
А	0.70	0.75	0.80	
A1	0.00	0.02	0.05	
A2	0.50	0.55	0.60	
А3	0.20REF			
b	0.30	0.35	0.40	
D	2.90	3.00	3.10	
E	2.90	3.00	3.10	
D2	1.60	1.70	1.80	
E2	2.30	2.40	2.50	
е	0.55	0.65	0.75	
K	0.40	0.50	0.60	
L	0.35	0.40	0.45	



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